PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Jong-Woo Ha	01/25/2010
Myung Kil Lee	11/07/2005
Hyun Uk Kim	11/07/2005
Taebok Jung	11/07/2005

RECEIVING PARTY DATA

Name:	STATS ChipPAC Ltd.
Street Address:	5 Yishun Street 23
City:	Singapore
State/Country:	SINGAPORE
Postal Code:	768442

PROPERTY NUMBERS Total: 1

Property Type	Number
Patent Number:	7279785

CH $40.00 7279785

CORRESPONDENCE DATA

Fax Number: (408)738-0881
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
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Email: efiling@ishimarulaw.com
Correspondent Name: Mikio Ishimaru
Address Line 1: Law Offices of Mikio Ishimaru
Address Line 2: 333 W. El Camino Real, Suite # 330
Address Line 4: Sunnyvale, CALIFORNIA 94087

ATTORNEY DOCKET NUMBER:	27-126
NAME OF SUBMITTER:	Mikio Ishimaru

Total Attachments: 5

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Docket No.: 27-126 CPAC 1104-1

ASSIGNMENT

WHEREAS, the undersigned (hereinafter termed Assignor(s)) has/have invented certain new and useful improvements in

STACKED DIE PACKAGE SYSTEM

for which United States patent application 11/164,160, filed November 12, 2005, has been executed on or before the date of this assignment;

WHEREAS, STATS ChipPAC Ltd., a Corporation of the Republic of Singapore, having a place of business at 5 Yishun Street 23, Singapore 768442 (hereinafter termed Assignee), is desirous of acquiring the entire right, title and interest in and to said application and said invention and improvements thereon, and in and to Letters Patents thereon when granted in the United States and foreign countries;
NOW, THEREFORE, for good and valuable consideration received by said Assignor(s) from said Assignee, the receipt of which is hereby acknowledged by said Assignor(s):

1. Said Assignor(s) does hereby sell, assign, transfer and convey unto said Assignee, the entire right, title and interest in and to said application and said invention and in and to any and all improvements on said invention and in and to any and all improvements on said invention heretofore or hereafter made or acquired by said Assignor(s); and in and to any and all Letters Patent on said invention and/or said improvements that may be granted in the United States or any foreign country, including each and every Letters Patent granted on any application which is a division, continuation, substitution, renewal, or continuation-in-part of any said application, and in and to each and every reissue or extension of said Letters Patent.

2. Said Assignor(s) hereby covenants and agrees to cooperate with said Assignee where said Assignee may enjoy to the fullest extent the right, title and interest herein conveyed. Such cooperation shall include (a) prompt execution of all papers (prepared at the expense of Assignee) which are deemed necessary or desirable by Assignee to perfect in it the right, title and interest herein conveyed, (b) prompt execution of all petitions, oaths, specifications or other papers (prepared at the expense of Assignee) which are deemed necessary or desirable by assignee for prosecuting said application, for filing and prosecuting divisional, continuation, substitution, renewal, continuation-in-part, or additional applications in the United States and/or foreign countries covering said invention and/or said improvements, for filing and prosecuting applications for reissuance of letters patent included herein, or for interference proceedings involving said invention and/or said improvements and (c) prompt assistance and cooperation in the prosecution of interference proceedings involving said invention and/or said improvements and in the adjudication of said Letters Patent, particularly by the disclosure of facts and the production of evidence relating to said invention and/or said improvements, provided the expenses which may be incurred by said Assignor(s) in lending such assistance and cooperation shall be paid by the Assignee.

3. The terms, covenants and conditions of this assignment shall inure to the benefit of said Assignee, its successors, assigns and/or other legal representatives and shall be binding upon said Assignor(s), his/her heirs, legal representatives and assigns.

4. Said Assignor(s) hereby warrants and represents that he/she has not entered into any assignment, contract or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

woo
Jong-Woo Ha

Jan. 25. 2010
Date

Witness Signature

Heejo Chi
Print Witness Name

Jan. 25. 2010
Date

Witness Signature

Kiyoun Jang
Print Witness Name

Jan. 25. 2010
Date

Docket No.: 27-126

ASSIGNMENT

WHEREAS, the undersigned (hereinafter termed Assignor(s)) has/have invented certain new and useful improvements in

STACKED DIE PACKAGE SYSTEM

for which a United States patent application has been executed on or before the date of this assignment;

WHEREAS, STATS ChipPAC Ltd., a Corporation of the Republic of Singapore, having a place of business at 5 Yishun Street 23, Singapore 768442 (hereinafter termed Assignee), is desirous of acquiring the entire right, title and interest in and to said application and said invention and improvements thereon, and in and to Letters Patents thereon when granted in the United States and foreign countries;

NOW, THEREFORE, for good and valuable consideration received by said Assignor(s) from said Assignee, the receipt of which is hereby acknowledged by said Assignor(s):

1. Said Assignor(s) does hereby sell, assign, transfer and convey unto said Assignee, the entire right, title and interest in and to said application and said invention and in and to any and all improvements on said invention and in and to any and all improvements on said invention heretofore or hereafter made or acquired by said Assignor(s); and in and to any and all Letters Patent on said invention and/or said improvements that may be granted in the United States or any foreign country, including each and every Letters Patent granted on any application which is a division, continuation, substitution, renewal, or continuation-in-part of any said application, and in and to each and every reissue or extension of said Letters Patent.

2. Said Assignor(s) hereby covenants and agrees to cooperate with said Assignee where said Assignee may enjoy to the fullest extent the right, title and interest herein conveyed. Such cooperation shall include (a) prompt execution of all papers (prepared at the expense of Assignee) which are deemed necessary or desirable by Assignee to perfect in it the right, title and interest herein conveyed, (b) prompt execution of all petitions, oaths, specifications or other papers (prepared at the expense of Assignee) which are deemed necessary or desirable by assignee for prosecuting said application, for filing and prosecuting divisional, continuation, substitution, renewal, continuation-in-part, or additional applications in the United States and/or foreign countries covering said invention and/or said improvements, for filing and prosecuting applications for reissuance of letters patent included herein, or for interference proceedings involving said invention and/or said improvements and (c) prompt assistance and cooperation in the prosecution of interference proceedings involving said invention and/or said improvements and in the adjudication of said Letters Patent, particularly by the disclosure of facts and the production of evidence relating to said invention and/or said improvements, provided the expenses which may be incurred by said Assignor(s) in lending such assistance and cooperation shall be paid by the Assignee.

3. The terms, covenants and conditions of this assignment shall inure to the benefit of said Assignee, its successors, assigns and/or other legal representatives and shall be binding upon said Assignor(s), his/her heirs, legal representatives and assigns.

4. Said Assignor(s) hereby warrants and represents that he/she has not entered into any assignment, contract or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

Jong-Woo Ha	OCT. 31 '2005 Date
Witness Signature	Witness Signature
Sang Ho Lee Print Witness Name	Shim Mee Seob Print Witness Name
11/7 '05 Date	11/7 '05 Date

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

Myung Kil Lee	Nov 07 2005 Date
Witness Signature	Witness Signature
Sang Ho Lee Print Witness Name	Shim Mee Seob Print Witness Name
11/7 '05 Date	11/7 '05 Date

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

Hyun Uk Kim	Nov. 07 '2005 Date
Witness Signature	Witness Signature
Sang Ho Lee Print Witness Name	Shim Mee Seob Print Witness Name
11/7 '05 Date	11/7 '05 Date

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

	Nov 07 ' 2005
Taebok Jung	Date
Witness Signature	Witness Signature
Sung Ho Lee	Shim Mee Seob
Print Witness Name	Print Witness Name
11/7 '05	11/7 '05
Date	Date